

ABSTRACT

A semiconductor device having a thinned semiconductor element allowed to be easily handled, and a method of manufacturing the device are provided. The semiconductor device includes a semiconductor element and a bumper member bonded, as a reinforcing member, to a back surface opposite to an electrode-formed surface of the semiconductor element with an adhesive. The adhesive has a low elastic modulus and easily expands and contracts after bonding, and bonds the semiconductor element to the bumper member while allowing the semiconductor element to be deformed. Thus, the semiconductor device can easily be handled, and the semiconductor element can be deformed in responsive to the deformation of a substrate after being mounted. In addition, a thermal stress in a heat cycle can be alleviated effectively.